

Name: SN65LVDS31\_LVDS33\_RevC\_BOM.xls  
Date:09/06/2017

# SN65LVDS31-33EVM

Bill O Page1

Item	Quar	Reference	Value	Part	Part_Number	PCB Footpri	Manufacturer
1	2	C1,C2	10uf		293D106X9035D2TE3	cc7343	Vishay Sprague
2	4	C3,C4,C5,C6	.01uf		08051C103JAT2A	cc0805	AVX Corporation
3	4	J1,J2,J3,J4	HEADER 3X1		HTSW-103-07-G-S	berg1x3	Samtec Inc.
4	10	P1,P2,P3,P4,J5,J6,P13,P14, P15,P16 P5,P6,P7,P8,P9,P10,P11,P1	Header 2x1		HTSW-102-07-G-S	berg2	Samtec Inc.
5	8	2	Header 2x2		TSW-102-07-G-D	BERG2X2	Samtec Inc.
6	1	P17	VCC1_3.3V			3267 bjack	Pomona
7	1	P18	GND			3267 bjack	Pomona
8	1	P19	VCC2_3.3V			3267 bjack	Pomona
9	1	P20	GND1			3267 bjack	Pomona
10	4	R1,R2,R3,R4		49.9	RMCF0603FT49R9	r0603	Stackpole Electronics Inc.
11	4	R5,R6,R7,R10		100	RMCF0603FT100R	r0603	Stackpole Electronics Inc.
12	2	R8,R9		0	RMCF0603ZT0R00	r0603	Stackpole Electronics Inc.
13	1	U1	LINE DRIVER		SN65LVDS31DR	D16	Texas Instruments
14	1	U2	LINE RECIEVER		SN65LVDS33DR	D16	Texas Instruments
15	1	PCB			SN65LVDS31-33EVM		Any

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